



1 Mbit (64Kb x16) Low Voltage OTP EPROM

- **LOW VOLTAGE READ OPERATION:**
2.7V to 3.6V
- **FAST READ ACCESS TIME:**
 - 70ns at $V_{CC} = 3.0V$ to 3.6V
 - 80ns at $V_{CC} = 2.7V$ to 3.6V
- **PIN COMPATIBLE** with M27C1024
- **LOW POWER CONSUMPTION:**
 - 15 μ A max Standby Current
 - 15mA max Active Current at 5MHz
- **PROGRAMMING TIME** 100 μ s/byte (typical)
- **HIGH RELIABILITY CMOS TECHNOLOGY**
 - 2,000V ESD Protection
 - 200mA Latchup Protection Immunity
- **ELECTRONIC SIGNATURE**
 - Manufacturer Code: 20h
 - Device Code: 8Ch

DESCRIPTION

The M27W102 is a low voltage 1 Mbit EPROM offered in the OTP range (one time programmable). It is ideally suited for microprocessor systems requiring large data or program storage and is organized as 65,536 words by 16 bits.

Table 1. Signal Names

| | |
|-----------|----------------|
| A0-A15 | Address Inputs |
| Q0-Q15 | Data Outputs |
| \bar{E} | Chip Enable |
| \bar{G} | Output Enable |
| \bar{P} | Program |
| V_{PP} | Program Supply |
| V_{CC} | Supply Voltage |
| V_{SS} | Ground |

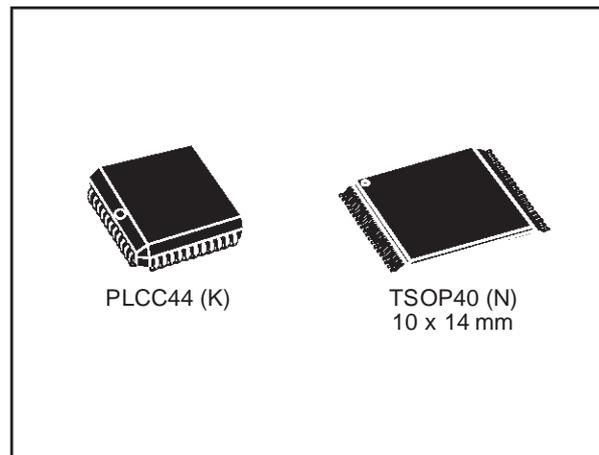


Figure 1. Logic Diagram

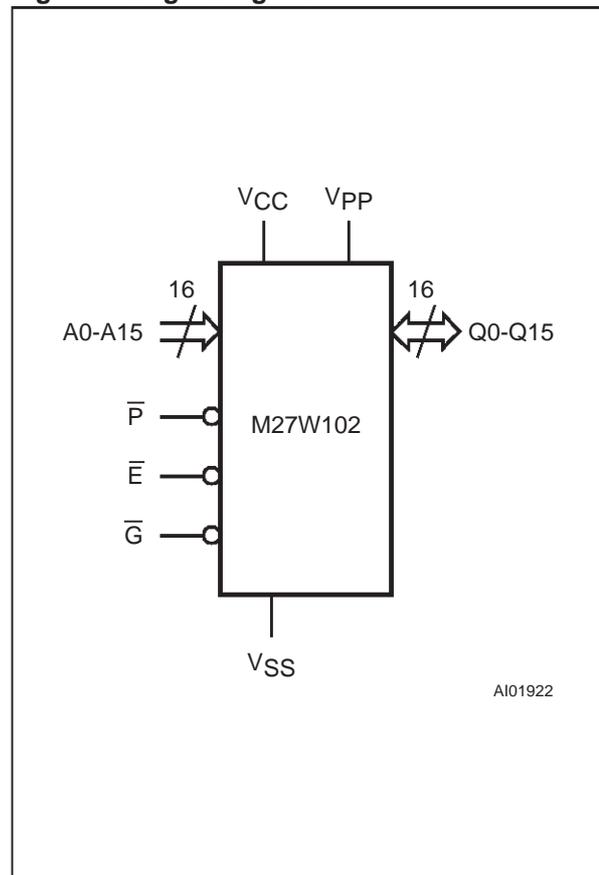
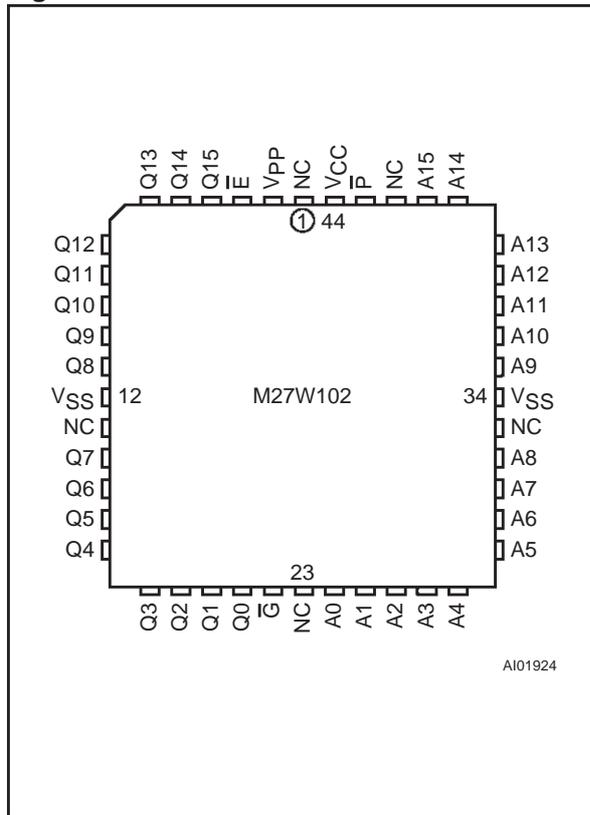
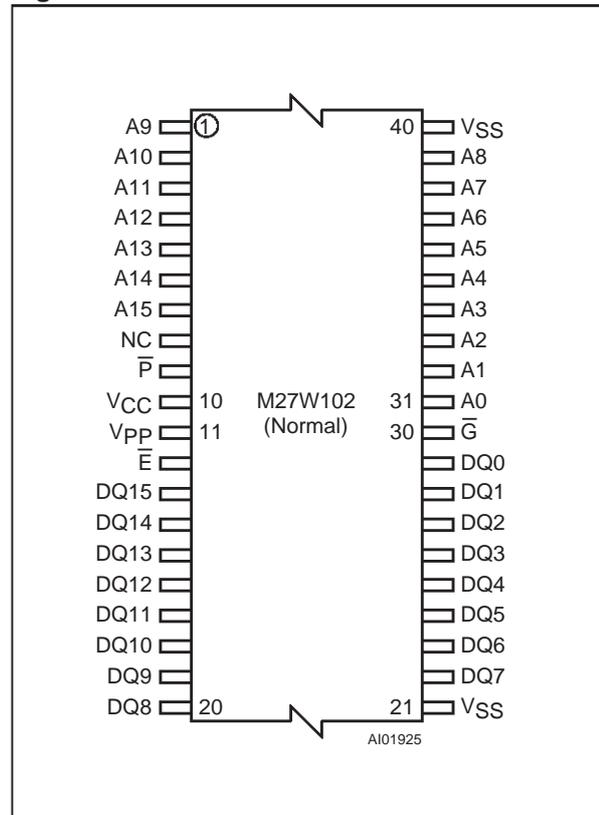


Figure 2A. LCC Pin Connections



Warning: NC = Not Connected.

Figure 2B. TSOP Pin Connections



Warning: NC = Not Connected.

Table 2. Absolute Maximum Ratings (1)

| Symbol | Parameter | Value | Unit |
|---------------------|-------------------------------------|------------|------|
| T _A | Ambient Operating Temperature (3) | -40 to 85 | °C |
| T _{BIAS} | Temperature Under Bias | -50 to 125 | °C |
| T _{STG} | Storage Temperature | -65 to 150 | °C |
| V _{IO} (2) | Input or Output Voltage (except A9) | -2 to 7 | V |
| V _{CC} | Supply Voltage | -2 to 7 | V |
| V _{A9} (2) | A9 Voltage | -2 to 13.5 | V |
| V _{PP} | Program Supply Voltage | -2 to 14 | V |

Note: 1. Except for the rating "Operating Temperature Range", stresses above those listed in the Table "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those indicated in the Operating sections of this specification is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability. Refer also to the STMicroelectronics SURE Program and other relevant quality documents.

2. Minimum DC voltage on Input or Output is -0.5V with possible undershoot to -2.0V for a period less than 20ns. Maximum DC voltage on Output is V_{CC} +0.5V with possible overshoot to V_{CC} +2V for a period less than 20ns.

3. Depends on range.

Table 3. Operating Modes

| Mode | \bar{E} | \bar{G} | \bar{P} | A9 | V _{PP} | Q0-Q15 |
|----------------------|-----------------|-----------------|-----------------------|-----------------|------------------------------------|-------------|
| Read | V _{IL} | V _{IL} | V _{IH} | X | V _{CC} or V _{SS} | Data Out |
| Output Disable | V _{IL} | V _{IH} | X | X | V _{CC} or V _{SS} | Hi-Z |
| Program | V _{IL} | X | V _{IL} Pulse | X | V _{PP} | Data Input |
| Verify | V _{IL} | V _{IL} | V _{IH} | X | V _{PP} | Data Output |
| Program Inhibit | V _{IH} | X | X | X | V _{PP} | Hi-Z |
| Standby | V _{IH} | X | X | X | V _{CC} or V _{SS} | Hi-Z |
| Electronic Signature | V _{IL} | V _{IL} | V _{IH} | V _{ID} | V _{CC} | Codes |

Note: X = V_{IH} or V_{IL}, V_{ID} = 12V ± 0.5V.

Table 4. Electronic Signature

| Identifier | A0 | Q7 | Q6 | Q5 | Q4 | Q3 | Q2 | Q1 | Q0 | Hex Data |
|---------------------|-----------------|----|----|----|----|----|----|----|----|----------|
| Manufacturer's Code | V _{IL} | 0 | 0 | 1 | 0 | 0 | 0 | 0 | 0 | 20h |
| Device Code | V _{IH} | 1 | 0 | 0 | 0 | 1 | 1 | 0 | 0 | 8Ch |

Note: X = V_{IH} or V_{IL}, V_{ID} = 12V ± 0.5V

The M27W102 operates in the read mode with a supply voltage as low as 2.7V at -40 to 85°C temperature range. The decrease in operating power allows either a reduction of the size of the battery or an increase in the time between battery recharges.

The M27W102 is offered in PLCC44 and TSOP40 (10 x 14mm) packages.

DEVICE OPERATION

The operating modes of the M27W102 are listed in the Operating Modes table. A single power supply is required in the read mode. All inputs are TTL levels except for V_{PP} and 12V on A9 for Electronic Signature.

Read Mode

The M27W102 has two control functions, both of which must be logically active in order to obtain data at the outputs. Chip Enable (\bar{E}) is the power control and should be used for device selection. Output Enable (\bar{G}) is the output control and should be used to gate data to the output pins, independent of device selection. Assuming that the addresses are stable, the address access time (t_{AVQV}) is equal to the delay from \bar{E} to output (t_{ELQV}). Data is available at the output after a delay of t_{OE} from the falling edge of \bar{G} , assuming that \bar{E} has been low and the addresses have been stable for at least t_{AVQV}-t_{GLQV}.

Standby Mode

The M27W102 has a standby mode which reduces the supply current from 15mA to 15μA with low voltage operation V_{CC} ≤ 3.6V, see Read Mode DC Characteristics table for details. The M27W102 is placed in the standby mode by applying a CMOS high signal to the \bar{E} input. When in the standby mode, the outputs are in a high impedance state, independent of the \bar{G} input.

Two Line Output Control

Because EPROMs are usually used in larger memory arrays, this product features a 2 line control function which accommodates the use of multiple memory connection. The two line control function allows:

- the lowest possible memory power dissipation,
- complete assurance that output bus contention will not occur.

For the most efficient use of these two control lines, \bar{E} should be decoded and used as the primary device selecting function, while \bar{G} should be made a common connection to all devices in the array and connected to the $\overline{\text{READ}}$ line from the system control bus. This ensures that all deselected memory devices are in their low power standby mode and that the output pins are only active when data is required from a particular memory device.

Table 5. AC Measurement Conditions

| | High Speed | Standard |
|---------------------------------------|------------|--------------|
| Input Rise and Fall Times | ≤ 10ns | ≤ 20ns |
| Input Pulse Voltages | 0 to 3V | 0.4V to 2.4V |
| Input and Output Timing Ref. Voltages | 1.5V | 0.8V and 2V |

Figure 3. AC Testing Input Output Waveform

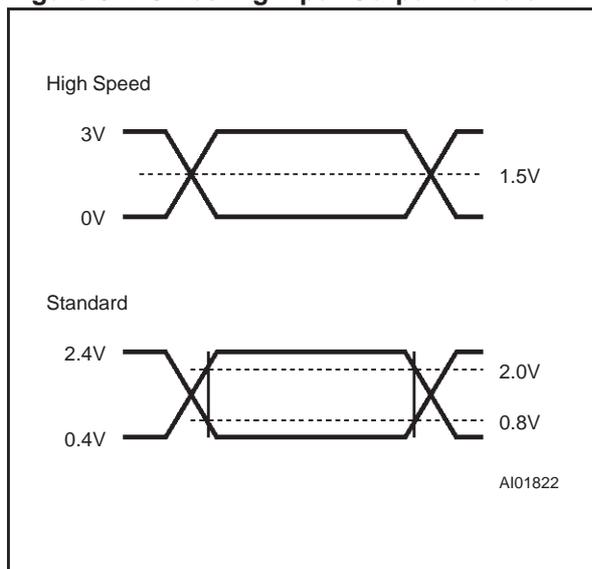


Figure 4. AC Testing Load Circuit

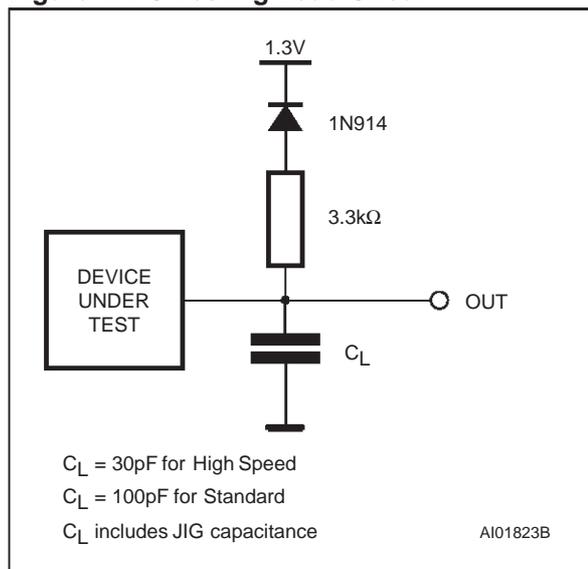


Table 6. Capacitance ⁽¹⁾ (T_A = 25 °C, f = 1 MHz)

| Symbol | Parameter | Test Condition | Min | Max | Unit |
|------------------|--------------------|-----------------------|-----|-----|------|
| C _{IN} | Input Capacitance | V _{IN} = 0V | | 6 | pF |
| C _{OUT} | Output Capacitance | V _{OUT} = 0V | | 12 | pF |

Note: Sampled only, not 100% tested.

System Considerations

The power switching characteristics of Advanced CMOS EPROMs require careful decoupling of the devices. The supply current, I_{CC}, has three segments that are of interest to the system designer: the standby current level, the active current level, and transient current peaks that are produced by the falling and rising edges of \bar{E} . The magnitude of transient current peaks is dependent on the capacitive and inductive loading of the device at the output.

The associated transient voltage peaks can be suppressed by complying with the two line output

control and by properly selected decoupling capacitors. It is recommended that a 0.1μF ceramic capacitor be used on every device between V_{CC} and V_{SS}. This should be a high frequency capacitor of low inherent inductance and should be placed as close to the device as possible. In addition, a 4.7μF bulk electrolytic capacitor should be used between V_{CC} and V_{SS} for every eight devices. The bulk capacitor should be located near the power supply connection point. The purpose of the bulk capacitor is to overcome the voltage drop caused by the inductive effects of PCB traces.

Table 7. Read Mode DC Characteristics (1)(T_A = -40 to 85°C; V_{CC} = 2.7V to 3.6V; V_{PP} = V_{CC})

| Symbol | Parameter | Test Condition | Min | Max | Unit |
|---------------------|-------------------------------|--|---------------------|-----------------------|------|
| I _{LI} | Input Leakage Current | 0V ≤ V _{IN} ≤ V _{CC} | | ±10 | μA |
| I _{LO} | Output Leakage Current | 0V ≤ V _{OUT} ≤ V _{CC} | | ±10 | μA |
| I _{CC} | Supply Current | $\bar{E} = V_{IL}, \bar{G} = V_{IL},$ I _{OUT} = 0mA, f = 5MHz, V _{CC} ≤ 3.6V | | 15 | mA |
| I _{CC1} | Supply Current (Standby) TTL | $\bar{E} = V_{IH}$ | | 1 | mA |
| I _{CC2} | Supply Current (Standby) CMOS | $\bar{E} > V_{CC} - 0.2V,$ V _{CC} ≤ 3.6V | | 15 | μA |
| I _{PP} | Program Current | V _{PP} = V _{CC} | | 100 | μA |
| V _{IL} | Input Low Voltage | | -0.6 | 0.2 V _{CC} | V |
| V _{IH} (2) | Input High Voltage | | 0.7 V _{CC} | V _{CC} + 0.5 | V |
| V _{OL} | Output Low Voltage | I _{OL} = 2.1mA | | 0.4 | V |
| V _{OH} | Output High Voltage TTL | I _{OH} = -400μA | 2.4 | | V |

Note: 1. V_{CC} must be applied simultaneously with or before V_{PP} and removed simultaneously or after V_{PP}.2. Maximum DC voltage on Output is V_{CC} + 0.5V.**Table 8. Read Mode AC Characteristics (1)**(T_A = -40 to 85°C; V_{CC} = 2.7V to 3.6V; V_{PP} = V_{CC})

| Symbol | Alt | Parameter | Test Condition | M27W102 | | | | | | Unit |
|-----------------------|------------------|---|---|--------------------------------|-----|--------------------------------|-----|--------------------------------|-----|------|
| | | | | -80 (3) | | | | -100 (-120/-150/-200) | | |
| | | | | V _{CC} = 3.0V to 3.6V | | V _{CC} = 2.7V to 3.6V | | V _{CC} = 2.7V to 3.6V | | |
| | | | | Min | Max | Min | Max | Min | Max | |
| t _{AVQV} | t _{ACC} | Address Valid to Output Valid | $\bar{E} = V_{IL},$ $\bar{G} = V_{IL}$ | | 70 | | 80 | | 100 | ns |
| t _{ELQV} | t _{CE} | Chip Enable Low to Output Valid | $\bar{G} = V_{IL}$ | | 70 | | 80 | | 100 | ns |
| t _{GLQV} | t _{OE} | Output Enable Low to Output Valid | $\bar{E} = V_{IL}$ | | 40 | | 50 | | 60 | ns |
| t _{EHQZ} (2) | t _{DF} | Chip Enable High to Output Hi-Z | $\bar{G} = V_{IL}$ | 0 | 40 | 0 | 50 | 0 | 60 | ns |
| t _{GHQZ} (2) | t _{DF} | Output Enable High to Output Hi-Z | $\bar{E} = V_{IL}$ | 0 | 40 | 0 | 50 | 0 | 60 | ns |
| t _{AXQX} | t _{OH} | Address Transition to Output Transition | $\bar{E} = V_{IL},$ $\bar{G} = V_{IL}$ | 0 | | 0 | | 0 | | ns |

Note: 1. V_{CC} must be applied simultaneously with or before V_{PP} and removed simultaneously or after V_{PP}.

2. Sampled only, not 100% tested.

3. Speed obtained with High Speed AC measurement conditions.

Figure 5. Read Mode AC Waveforms

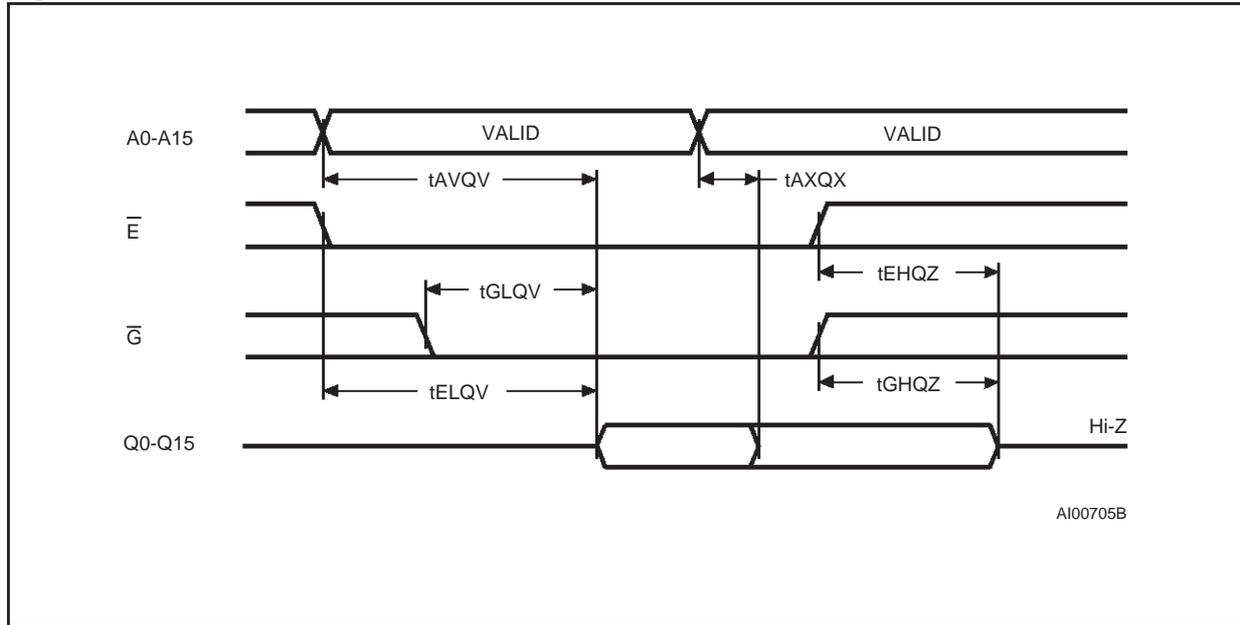


Table 9. Programming Mode AC Characteristics (1)
 ($T_A = 25\text{ }^\circ\text{C}$; $V_{CC} = 6.25\text{V} \pm 0.25\text{V}$; $V_{PP} = 12.75\text{V} \pm 0.25\text{V}$)

| Symbol | Parameter | Test Condition | Min | Max | Unit |
|----------|-------------------------|-------------------------------------|------|----------------|---------------|
| I_{LI} | Input Leakage Current | $0\text{V} \leq V_{IN} \leq V_{IH}$ | | ± 10 | μA |
| I_{CC} | Supply Current | | | 50 | mA |
| I_{PP} | Program Current | $\bar{E} = V_{IL}$ | | 50 | mA |
| V_{IL} | Input Low Voltage | | -0.3 | 0.8 | V |
| V_{IH} | Input High Voltage | | 2 | $V_{CC} + 0.5$ | V |
| V_{OL} | Output Low Voltage | $I_{OL} = 2.1\text{mA}$ | | 0.4 | V |
| V_{OH} | Output High Voltage TTL | $I_{OH} = -400\mu\text{A}$ | 2.4 | | V |
| V_{ID} | A9 Voltage | | 11.5 | 12.5 | V |

Note: 1. V_{CC} must be applied simultaneously with or before V_{PP} and removed simultaneously or after V_{PP} .

Table 10. Programming Mode AC Characteristics (1)
 ($T_A = 25\text{ }^\circ\text{C}$; $V_{CC} = 6.25\text{V} \pm 0.25\text{V}$; $V_{PP} = 12.75\text{V} \pm 0.25\text{V}$)

| Symbol | Alt | Parameter | Test Condition | Min | Max | Unit |
|------------------|-----------|--|----------------|-----|-----|---------------|
| t_{AVPL} | t_{AS} | Address Valid to Program Low | | 2 | | μs |
| t_{QVPL} | t_{DS} | Input Valid to Program Low | | 2 | | μs |
| t_{VPHPL} | t_{VPS} | VPP High to Program Low | | 2 | | μs |
| t_{VCHPL} | t_{VCS} | VCC High to Program Low | | 2 | | μs |
| t_{ELPL} | t_{CES} | Chip Enable Low to Program Low | | 2 | | μs |
| t_{PLPH} | t_{PW} | Program Pulse Width | | 95 | 105 | μs |
| t_{PHQX} | t_{DH} | Program High to Input Transition | | 2 | | μs |
| t_{QXGL} | t_{OES} | Input Transition to Output Enable Low | | 2 | | μs |
| t_{GLQV} | t_{OE} | Output Enable Low to Output Valid | | | 100 | ns |
| $t_{GHQZ}^{(2)}$ | t_{DFP} | Output Enable High to Output Hi-Z | | 0 | 130 | ns |
| t_{GHAX} | t_{AH} | Output Enable High to Address Transition | | 0 | | ns |

Note: 1. V_{CC} must be applied simultaneously with or before V_{PP} and removed simultaneously or after V_{PP} .
 2. Sampled only, not 100% tested.

Figure 6. Programming and Verify Modes AC Waveforms

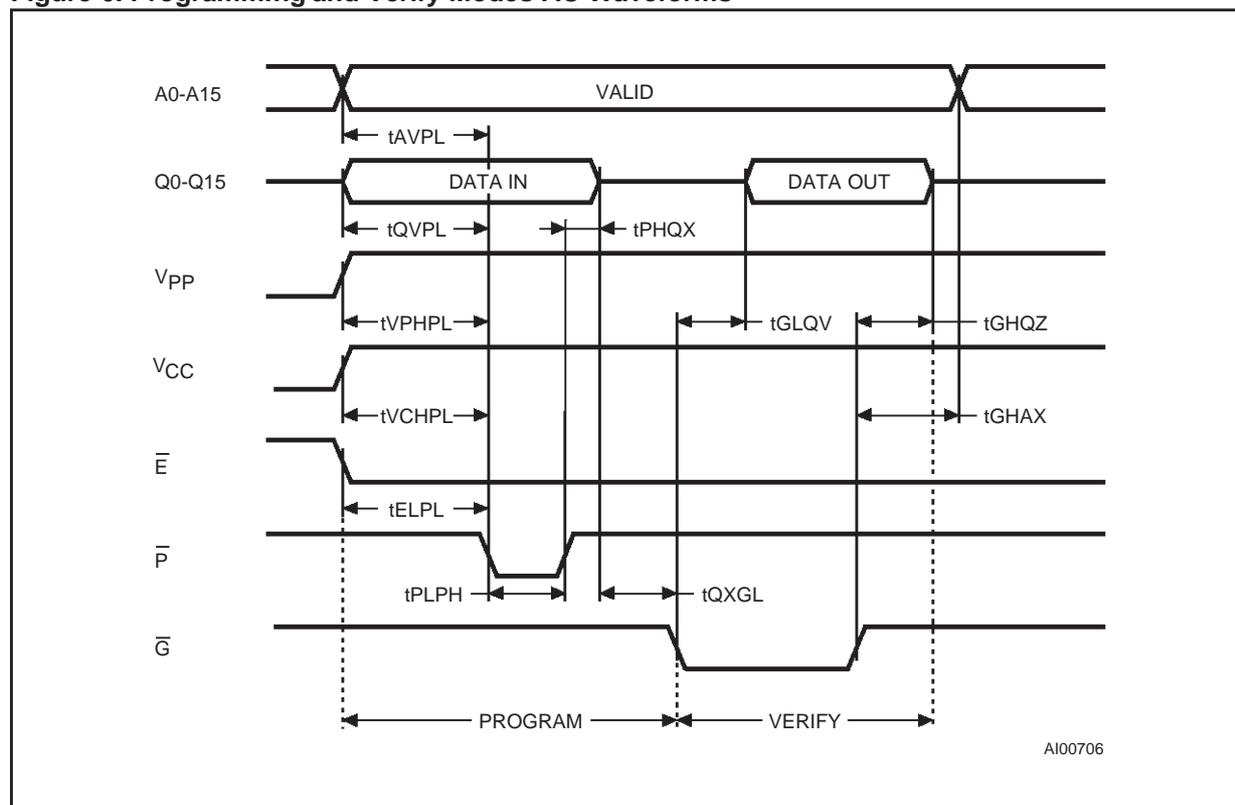
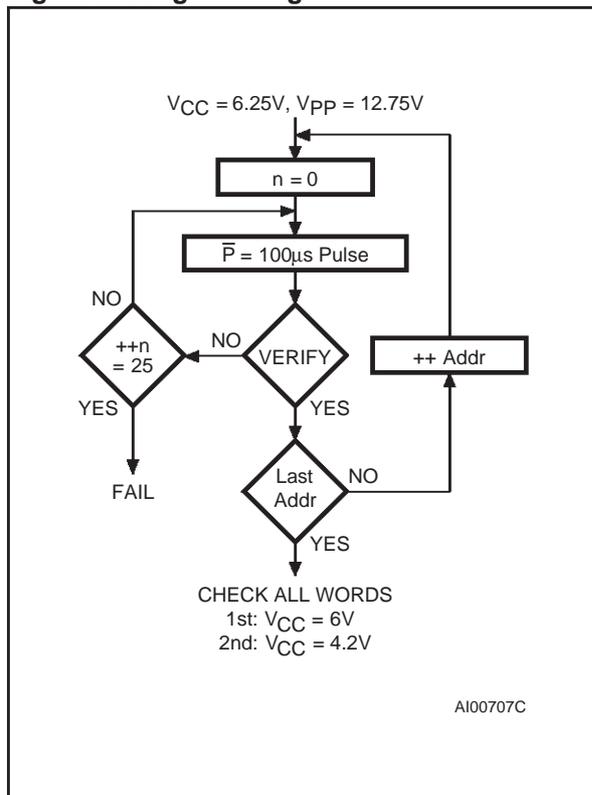


Figure 7. Programming Flowchart



Programming

The M27W102 has been designed to be fully compatible with the M27C1024 and has the same electronic signature. As a result the M27W102 can be programmed as the M27C1024 on the same programming equipment applying 12.75V on V_{PP} and 6.25V on V_{CC} by the use of the same PRESTO II algorithm.

When delivered, all bits of the M27W102 are in the '1' state. Data is introduced by selectively programming '0's into the desired bit locations. Although only '0's will be programmed, both '1's and '0's can be present in the data word. The M27W102 is in the programming mode when V_{PP} input is at 12.75V, \bar{E} is at V_{IL} and \bar{P} is pulsed to V_{IL} . The data to be programmed is applied to 16 bits in parallel to the data output pins. The levels required for the address and data inputs are TTL. V_{CC} is specified to be $6.25V \pm 0.25V$.

PRESTO II Programming Algorithm

PRESTO II Programming Algorithm allows programming of the whole array with a guaranteed margin, in a typical time of 6.5 seconds. Program-

ming with PRESTO II consists of applying a sequence of 100µs program pulses to each word until a correct verify occurs (see Figure 7). During programming and verify operation, a MARGIN MODE circuit is automatically activated in order to guarantee that each cell is programmed with enough margin. No overprogram pulse is applied since the verify in MARGIN MODE at V_{CC} much higher than 3.6V, provides necessary margin to each programmed cell.

Program Inhibit

Programming of multiple M27W102s in parallel with different data is also easily accomplished. Except for \bar{E} , all like inputs including \bar{G} of the parallel M27W102 may be common. A TTL low level pulse applied to a M27W102's \bar{P} input, with \bar{E} low and V_{PP} at 12.75V, will program that M27W102. A high level \bar{E} input inhibits the other M27W102s from being programmed.

Program Verify

A verify (read) should be performed on the programmed bits to determine that they were correctly programmed. The verify is accomplished with \bar{E} and \bar{G} at V_{IL} , \bar{P} at V_{IH} , V_{PP} at 12.75V and V_{CC} at 6.25V.

On-Board Programming

The M27W102 can be directly programmed in the application circuit. See the relevant Application Note AN620.

Electronic Signature

The Electronic Signature (ES) mode allows the reading out of a binary code from an EPROM that will identify its manufacturer and type. This mode is intended for use by programming equipment to automatically match the device to be programmed with its corresponding programming algorithm. The ES mode is functional in the $25^{\circ}\text{C} \pm 5^{\circ}\text{C}$ ambient temperature range that is required when programming the M27W102. To activate the ES mode, the programming equipment must force 11.5V to 12.5V on address line A9 of the M27W102 with $V_{PP} = V_{CC} = 5V$. Two identifier bytes may then be sequenced from the device outputs by toggling address line A0 from V_{IL} to V_{IH} . All other address lines must be held at V_{IL} during Electronic Signature mode. Byte 0 ($A0=V_{IL}$) represents the manufacturer code and byte 1 ($A0=V_{IH}$) the device identifier code. For the STMicroelectronics M27W102, these two identifier bytes are given in Table 4 and can be read-out on outputs Q0 to Q7.

Note that the M27W102 and M27C1002 have the same identifier byte.

Table 11. Ordering Information Scheme

| | | | | | |
|--|---------|-----|---|---|----|
| Example: | M27W102 | -80 | K | 6 | TR |
| Device Type | | | | | |
| Speed | | | | | |
| -80 ^(1,2) = 80 ns | | | | | |
| -100 = 100 ns | | | | | |
| Not for New Design ⁽³⁾ | | | | | |
| -120 = 120 ns | | | | | |
| -150 = 150 ns | | | | | |
| -200 = 200 ns | | | | | |
| Package | | | | | |
| K = PLCC44 | | | | | |
| N = TSOP40: 10 x 14mm | | | | | |
| Temperature Range | | | | | |
| 6 = -40 to 85°C | | | | | |
| Option | | | | | |
| TR = Tape & Reel Packing | | | | | |

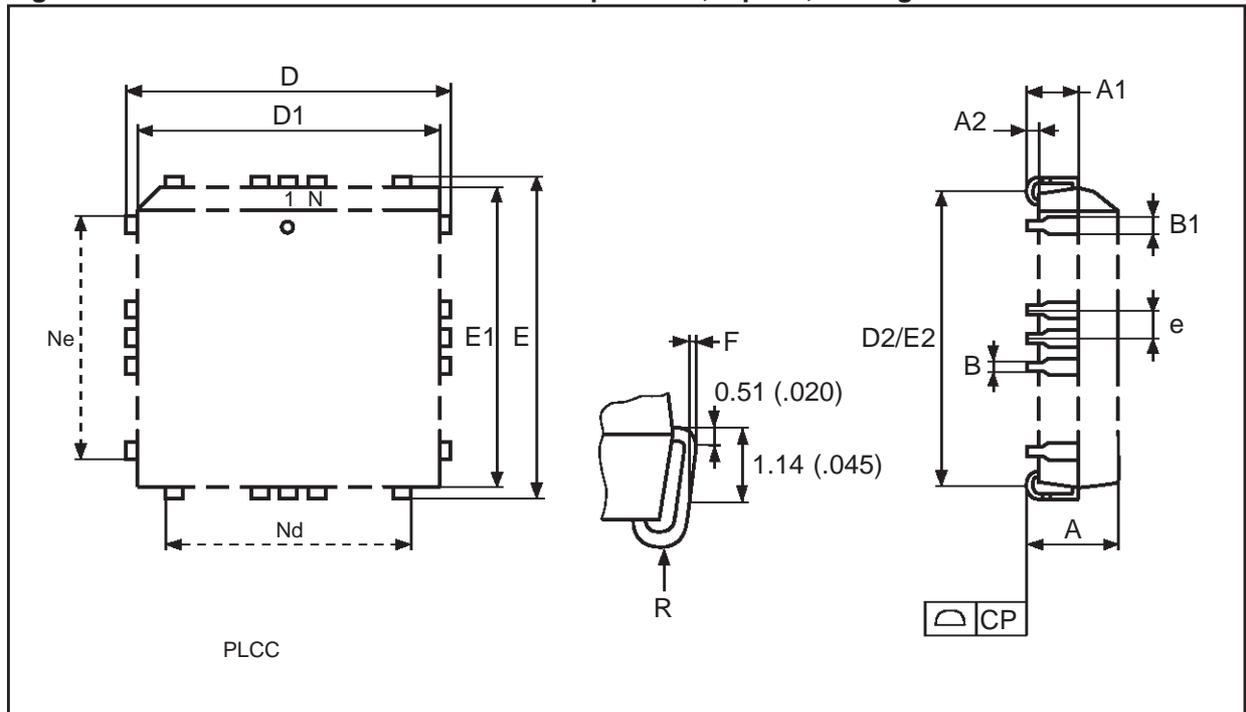
Note: 1. High Speed, see AC Characteristics section for further information.
 2. This speed also guarantees 70ns access time at $V_{CC} = 3.0V$ to $3.6V$.
 3. These speeds are replaced by the 100ns.

For a list of available options (Speed, Package, etc...) or for further information on any aspect of this device, please contact the ST Sales Office nearest to you.

Table 12. PLCC44 - 44 lead Plastic Leaded Chip Carrier, square, Package Mechanical Data

| Symb | mm | | | inches | | |
|------|------|-------|-------|--------|-------|-------|
| | Typ | Min | Max | Typ | Min | Max |
| A | | 4.20 | 4.70 | | 0.165 | 0.185 |
| A1 | | 2.29 | 3.04 | | 0.090 | 0.120 |
| A2 | | – | 0.51 | | – | 0.020 |
| B | | 0.33 | 0.53 | | 0.013 | 0.021 |
| B1 | | 0.66 | 0.81 | | 0.026 | 0.032 |
| D | | 17.40 | 17.65 | | 0.685 | 0.695 |
| D1 | | 16.51 | 16.66 | | 0.650 | 0.656 |
| D2 | | 14.99 | 16.00 | | 0.590 | 0.630 |
| E | | 17.40 | 17.65 | | 0.685 | 0.695 |
| E1 | | 16.51 | 16.66 | | 0.650 | 0.656 |
| E2 | | 14.99 | 16.00 | | 0.590 | 0.630 |
| e | 1.27 | – | – | 0.050 | – | – |
| F | | 0.00 | 0.25 | | 0.000 | 0.010 |
| R | 0.89 | – | – | 0.035 | – | – |
| N | 44 | | | 44 | | |
| CP | | | 0.10 | | | 0.004 |

Figure 8. PLCC44 - 44 lead Plastic Leaded Chip Carrier, square, Package Outline

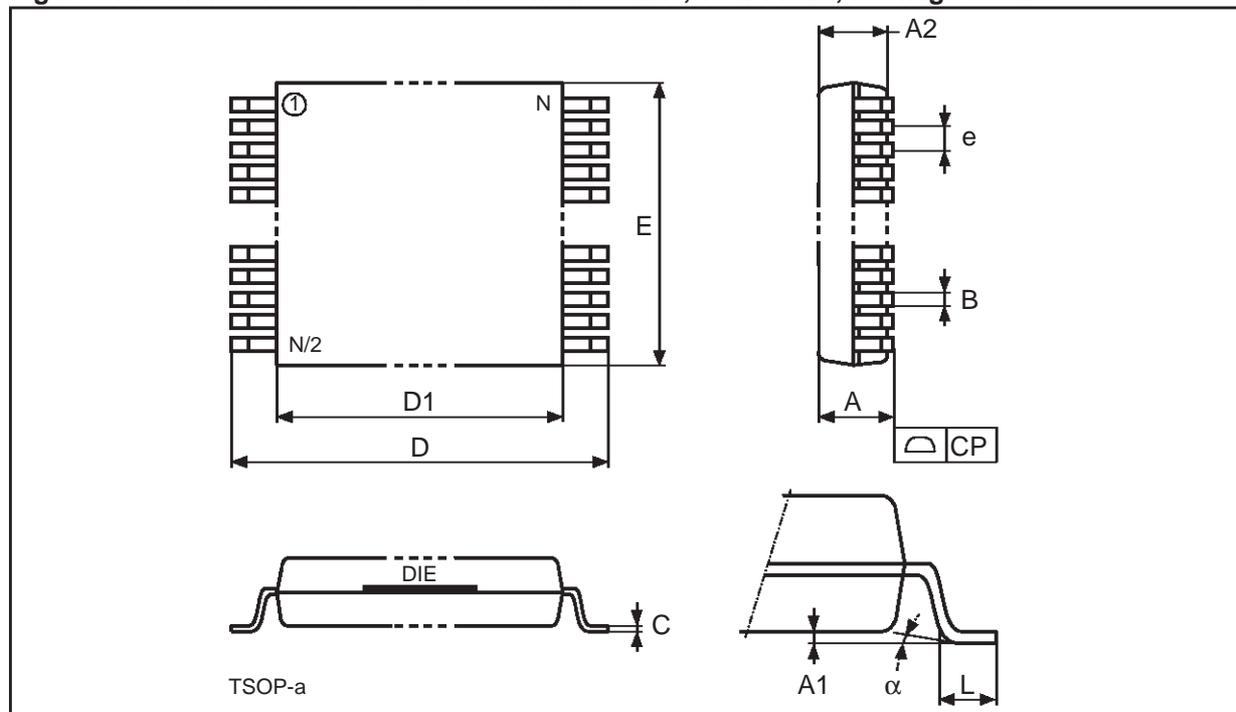


Drawing is not to scale.

Table 13. TSOP40 - 40 lead Plastic Thin Small Outline, 10 x 14mm, Package Mechanical Data

| Symb | mm | | | inches | | |
|----------|------|-------|-------|--------|-------|-------|
| | Typ | Min | Max | Typ | Min | Max |
| A | | | 1.20 | | | 0.047 |
| A1 | | 0.05 | 0.15 | | 0.002 | 0.006 |
| A2 | | 0.95 | 1.05 | | 0.037 | 0.041 |
| B | | 0.17 | 0.27 | | 0.007 | 0.011 |
| C | | 0.10 | 0.21 | | 0.004 | 0.008 |
| D | | 13.80 | 14.20 | | 0.543 | 0.559 |
| D1 | | 12.30 | 12.50 | | 0.484 | 0.492 |
| E | | 9.90 | 10.10 | | 0.390 | 0.398 |
| e | 0.50 | – | – | 0.020 | – | – |
| L | | 0.50 | 0.70 | | 0.020 | 0.028 |
| α | | 0° | 5° | | 0° | 5° |
| N | 40 | | | 40 | | |
| CP | | | 0.10 | | | 0.004 |

Figure 9. TSOP40 - 40 lead Plastic Thin Small Outline, 10 x 14mm, Package Outline



Drawing is not to scale.

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